

# **TK16H60C-VB** Datasheet

N-Channel 600 V (D-S) Super Junction Power MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	600					
R <sub>DS(on)</sub> at 25 °C (Ω)	$V_{GS} = 10 V$	0.23				
Q <sub>g</sub> Typ. (nC)	24					
Q <sub>gs</sub> (nC)	6					
Q <sub>gd</sub> (nC)	11					
Configuration	Single					

### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>a</sub>)
- Avalanche energy rated (UIS)



## TO-3P G G D D (TAB) S s N-Channel MOSFET

- **APPLICATIONS**
- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> :	= 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V <sub>DS</sub>	600	N/	
Gate-Source Voltage			V <sub>GS</sub>	± 30	V	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C T <sub>C</sub> = 100 °C	- I <sub>D</sub>	15		
	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		10	А	
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	45		
Linear Derating Factor				1.4	W/°C	
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	286	mJ	
Maximum Power Dissipation			PD	180	W	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-Source Voltage Slope	T <sub>J</sub> = 125 °C		-l\ / / -lt	37		
Reverse Diode dV/dt <sup>d</sup>			dV/dt	23	V/ns	
Soldering Recommendations (Peak Temperature) <sup>c</sup>	for 10 s			300	°C	

#### Notes

a. Repetitive rating; pulse width limited by maximum junction temperature. b.  $V_{DD} = 50$  V, starting T<sub>J</sub> = 25 °C, L = 28.2 mH, R<sub>g</sub> = 25  $\Omega$ , I<sub>AS</sub> = 4.5 A.

c. 1.6 mm from case.

d.  $I_{SD} \leq I_D$ , dl/dt = 100 A/µs, starting  $T_J$  = 25 °C.



THERMAL RESISTANCE RATI	NGS								
PARAMETER	SYMBOL	TYP. MAX.			UNIT				
Maximum Junction-to-Ambient	R <sub>thJA</sub>	- 62							
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	- 0.7				°C/W			
SPECIFICATIONS (T <sub>J</sub> = 25 $^{\circ}$ C, u	inless otherwi	se noted)							
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT	
Static	<u>.</u>	•			•		•	•	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> =	= 0 V, I <sub>D</sub> =	250 µA	600	-	-		
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I <sub>D</sub> = 1 mA		I <sub>D</sub> = 1 mA	-	0.75	-	V/°C	
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> =	250 µA	2	-	4	V	
		$V_{GS} = \pm 20 V$ $V_{GS} = \pm 30 V$		-	-	± 100	nA		
Gate-Source Leakage	I <sub>GSS</sub>			-	-	± 1	μA		
		$V_{DS} = 600 \text{ V}, \text{ V}_{GS} = 000 \text{ V}$		-	-	1	<u> </u>		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		$V_{DS} = 520 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			-	10	μA	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V		$I_D = 8 A$	-	0.23	-	Ω	
Forward Transconductance		V <sub>DS</sub>	= 30 V, I <sub>D</sub>	= 8 A	-	5.6	-	S	
Dynamic					1	1	1		
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$ f = 1 MHz		-	1640	-	pF		
Output Capacitance	C <sub>oss</sub>			-	80	-			
Reverse Transfer Capacitance	C <sub>rss</sub>			-	4	-			
Effective Output Capacitance, Energy Related <sup>a</sup>	C <sub>o(er)</sub>	$V_{DS} = 0 V $ to 520 V, $V_{GS} = 0 V$		-	63	-			
Effective Output Capacitance, Time Related <sup>b</sup>	C <sub>o(tr)</sub>			-	213	-			
Total Gate Charge	Qg				-	24	48		
Gate-Source Charge	Q <sub>gs</sub>	$V_{GS} = 10 V$ $I_D = 8 J$		A, V <sub>DS</sub> = 520 V	-	6	-	nC	
Gate-Drain Charge	Q <sub>gd</sub>				-	11	-		
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{DD}$ = 520V, I $_D$ = 8 A, $V_{GS}$ = 10 V, $R_g$ = 9.1 $\Omega$		-	18	36	- ns		
Rise Time	t <sub>r</sub>			-	24	48			
Turn-Off Delay Time	t <sub>d(off)</sub>			-	48	96			
Fall Time	t <sub>f</sub>			-	25	50			
Gate Input Resistance	Rg	f = 1 MHz, open drain		-	0.8	-	Ω		
Drain-Source Body Diode Characteristi	cs	T			1			1	
Continuous Source-Drain Diode Current	ا <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	15	A		
Pulsed Diode Forward Current	I <sub>SM</sub>			-	-	38			
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 8 A, V <sub>GS</sub> = 0 V		-	-	1.2	V		
Reverse Recovery Time	t <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = I_S = 8 \text{ A},$ dl/dt = 100 A/µs, V <sub>R</sub> = 400 V		-	325	-	ns		
Reverse Recovery Charge	Q <sub>rr</sub>			-	4.6	-	μC		
Reverse Recovery Current	I <sub>RRM</sub>			<u> </u>	20				

#### Notes

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ . b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

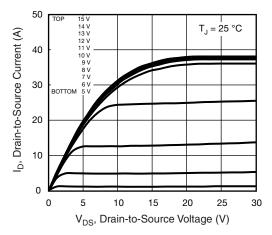


Fig. 1 - Typical Output Characteristics

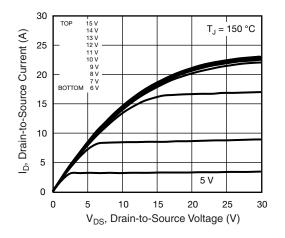


Fig. 2 - Typical Output Characteristics

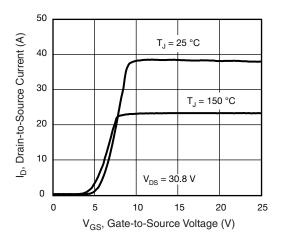


Fig. 3 - Typical Transfer Characteristics

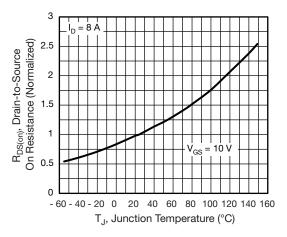


Fig. 4 - Normalized On-Resistance vs. Temperature

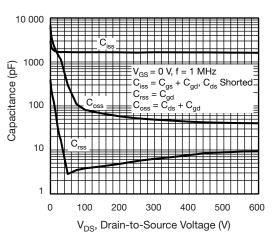


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

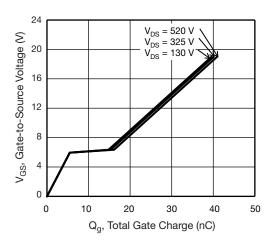


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

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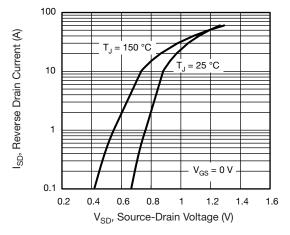


Fig. 7 - Typical Source-Drain Diode Forward Voltage

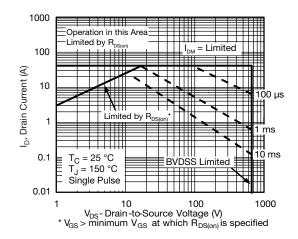


Fig. 8 - Maximum Safe Operating Area

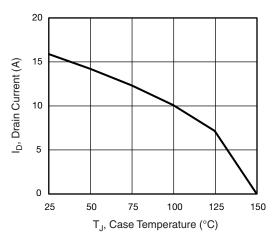


Fig. 9 - Maximum Drain Current vs. Case Temperature

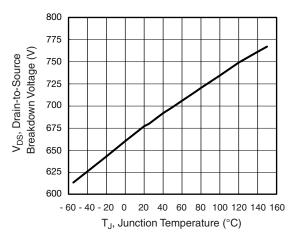


Fig. 10 - Temperature vs. Drain-to-Source Voltage

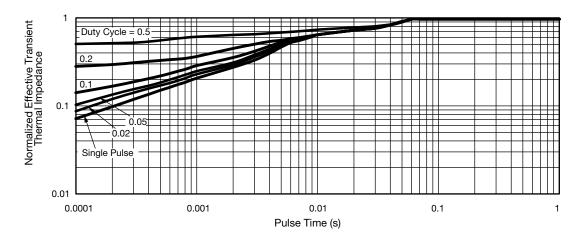


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case



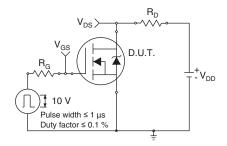


Fig. 12 - Switching Time Test Circuit

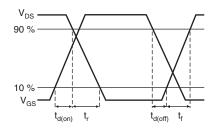


Fig. 13 - Switching Time Waveforms

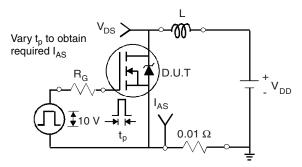


Fig. 14 - Unclamped Inductive Test Circuit

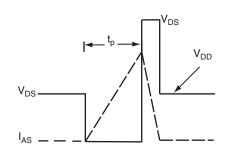


Fig. 15 - Unclamped Inductive Waveforms

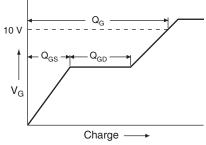


Fig. 16 - Basic Gate Charge Waveform

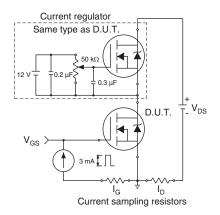
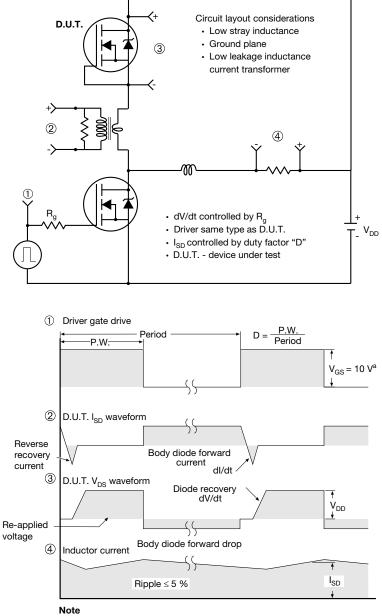


Fig. 17 - Gate Charge Test Circuit



#### Peak Diode Recovery dV/dt Test Circuit

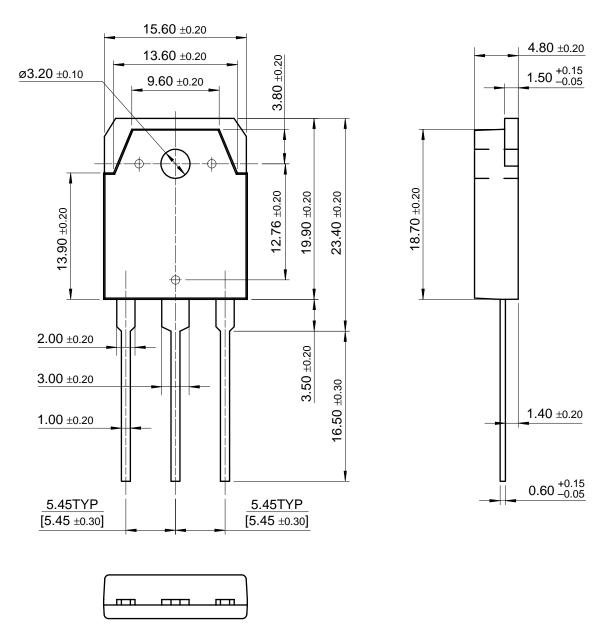


a.  $V_{GS} = 5$  V for logic level devices

Fig. 18 - For N-Channel



TO-3P





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